

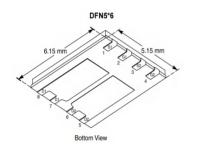
# Dual N-Channel 150V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A) <sup>a</sup>		
150	0.090 at V <sub>GS</sub> = 10 V	8		
	0.100 at V <sub>GS</sub> = 4.5 V	6		

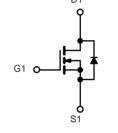
### **FEATURES**

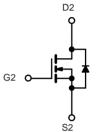
- 175 °C Junction Temperature
- Trench technology Power MOSFET
- Material categorization:











Top View

Bottom View

N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current (T <sub>.1</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 25 °C	L	8		
Continuous Drain Current (1) = 175 °C)	T <sub>C</sub> = 100 °C	l <sub>D</sub>	6.4 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	24	А		
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	76 <sup>a</sup>			
Avalanche Current	I <sub>AS</sub>	82			
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E <sub>AS</sub>	110	mJ	
Mayimum Dayar Dissination	T <sub>C</sub> = 25 °C	P <sub>D</sub>	136	W	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C		3 <sup>b</sup> , 8.3 <sup>b, c</sup>	]	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maniana landina to Andria 18	t ≤ 10 sec	R <sub>thJA</sub>	15	18	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State	™thJA	60	50		
Maximum Junction-to-Case		R <sub>thJC</sub>	0.85	1.1		

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c.  $t \le 10 \text{ s}$ .

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Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static	Oymbor	rest containens	1411111	тур.	mux.	O.I.I.	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	150				
Gate Threshold Voltage	V <sub>GS(th)</sub>			2	3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
,		V <sub>DS</sub> = 7 5 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 75V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μA	
3		V <sub>DS</sub> = 75V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	60			Α	
	. ,	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.90			
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.135			
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175 °C		0.225		Ω	
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 12A		0.100			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		60		S	
Dynamic			I.		l l		
Input Capacitance	C <sub>iss</sub>			600			
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}$		470		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			225			
Total Gate Charge <sup>c</sup>	$Q_g$			89	70		
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		26		nC	
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			23			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			21	25		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 100 \text{ V}, R_{L} = 0.6 \Omega$		15	25	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		35	50		
Fall Time <sup>c</sup>	t <sub>f</sub>			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)					
Pulsed Current	I <sub>SM</sub>				24	Α	
Diode Forward Voltage	V <sub>SD</sub>	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		1	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs		4	135	ns	

#### Notes:

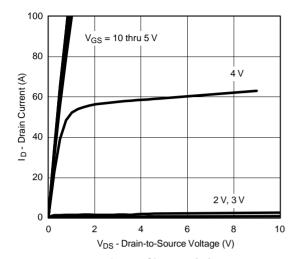
- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

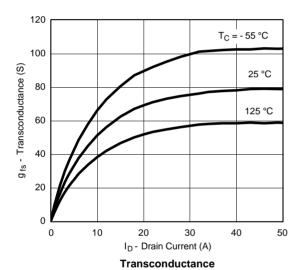
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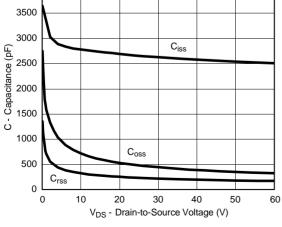
### TYPICAL CHARACTERISTICS (25 °C unless noted)



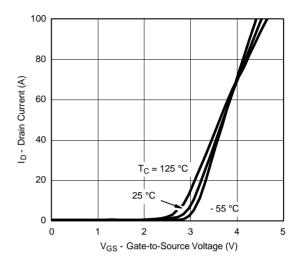
### **Output Characteristics**



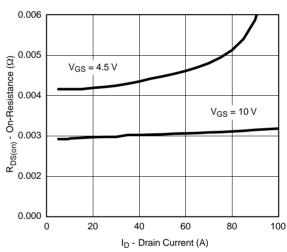
# 3500 3000 $C_{\text{iss}}$



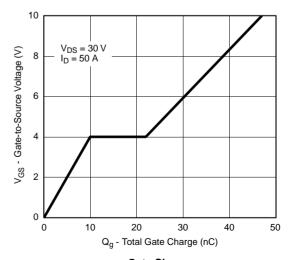
Capacitance



**Transfer Characteristics** 



On-Resistance vs. Drain Current



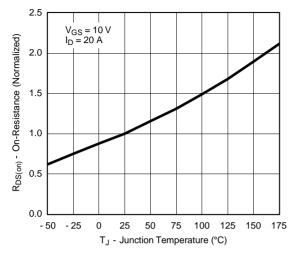
**Gate Charge** 

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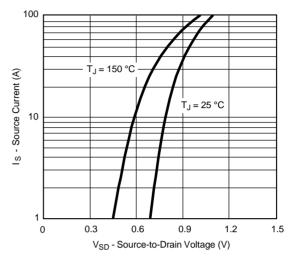
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## TYPICAL CHARACTERISTICS (25 °C unless noted)



On-Resistance vs. Junction Temperature



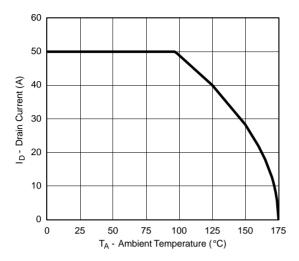
Source-Drain Diode Forward Voltage

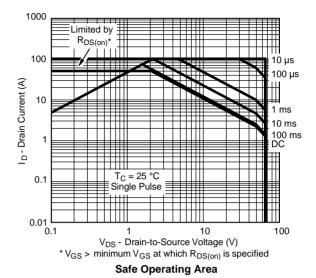
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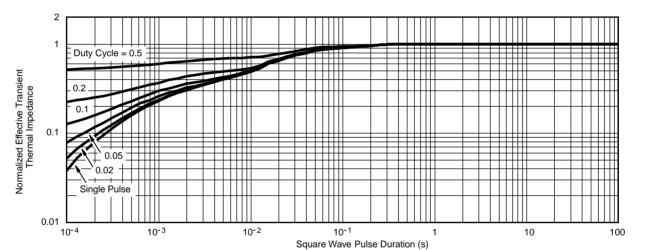
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### **THERMAL RATINGS**





Maximum Drain Current vs. Ambient Temperature

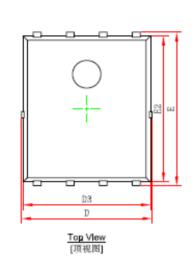


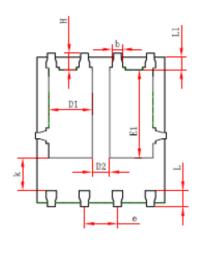
Normalized Thermal Transient Impedance, Junction-to-Case

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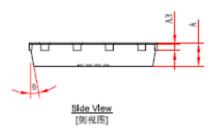


### PDFNWB5×6-8L-A PACKAGE OUTLINE DIMENSIONS





Bottom View [背视图]



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	0.900	1.000	0.035	0.039	
A3	0.254	REF.	0.010	REF.	
D	4.944	5.096	0.195	0.201	
E	5.974	6.126	0.235	0.241	
D1	1.470	1.870	0.058	0.074	
D2	0.470	0.870	0.019	0.034	
E1	3.375	3.575	0.133	0.141	
D3	4.824	4.976	0.190	0.196	
E2	5.674	5.826	0.223	0.229	
k	1.190	1.390	0.047	0.055	
b	0.350	0.450	0.014	0.018	
e	1.270TYP.		0.050TYP.		
L	0.559	0.711	0.022	0.028	
L1	0.424	0.576	0.017	0.023	
Н	0.574	0.726	0.023	0.029	
θ	10°	12°	10°	12°	

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